

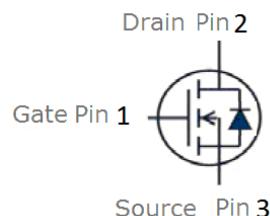
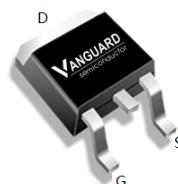
Features

- N-Channel, 5V Logic Level Control
- Enhancement mode
- Very low on-resistance @ $V_{GS}=4.5$ V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant



V_{DS}	100	V
$R_{DS(on),typ}@VGS=10V$	78	$m\Omega$
$R_{DS(on),typ}@VGS=4.5V$	82	$m\Omega$
I_D	15	A

TO-252



Part ID	Package Type	Marking	Tape and reel information
VSD090N10MS	TO-252	090N10	2500pcs/Reel

Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	100	V
V_{GS}	Gate-Source voltage	± 20	V
I_D	Continuous drain current@ $V_{GS}=10V$	$T_c=25^\circ C$	A
		$T_c=70^\circ C$	A
I_{DM}	Pulse drain current tested ①	$T_c=25^\circ C$	A
P_D	Maximum power dissipation	$T_c=25^\circ C$	W
I_s	Diode Continuous Forward Current	$T_c=25^\circ C$	A
I_{AS}	Avalanche Current Max	$L=0.5mH$	A
E_{AS}	Avalanche energy, single pulsed ②	9	mJ
T_{STG}, T_J	Storage and operating temperature range	-55 to 175	°C

Thermal characteristics

$R_{\theta JA}$	Thermal Resistance Junction-Ambient	60	°C/W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	5	°C/W



Typical Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	100	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_D=250\mu\text{A}$	1.0	2.0	3.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=10\text{V}, I_D=10\text{A}$	--	78	90	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^③	$V_{\text{GS}}=4.5\text{V}, I_D=5\text{A}$	--	82	100	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	--	525	--	pF
C_{oss}	Output Capacitance		--	41	--	pF
C_{rss}	Reverse Transfer Capacitance		--	36	--	pF
R_g	Gate Resistance		--	2.6	--	Ω
Q_g	Total Gate Charge	$V_{\text{DS}}=50\text{V}, I_D=3\text{A}, V_{\text{GS}}=10\text{V}$	--	15.6	--	nC
Q_{gs}	Gate-Source Charge		--	3.2	--	nC
Q_{gd}	Gate-Drain Charge		--	4.4	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=50\text{V}, I_D=1\text{A}, R_g=6.8\Omega, V_{\text{GS}}=4.5\text{V}$	--	8	--	nS
t_r	Turn-on Rise Time		--	4.5	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	26	--	nS
t_f	Turn-Off Fall Time		--	3.8	--	nS
Source- Drain Diode Characteristics@ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=10\text{A}, V_{\text{GS}}=0\text{V}$	--	0.89	1.20	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_{\text{sd}}=10\text{A}, V_{\text{GS}}=0\text{V}$ $dI/dt=500\text{A}/\mu\text{s}$	--	26	--	nS
Q_{rr}	Reverse Recovery Charge		--	115	--	nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature
- ② Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_g = 25\Omega$, $I_{\text{AS}} = 6\text{A}$, $V_{\text{GS}} = 10\text{V}$. Part not recommended for use above this value.
- ③ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.



Typical Characteristics

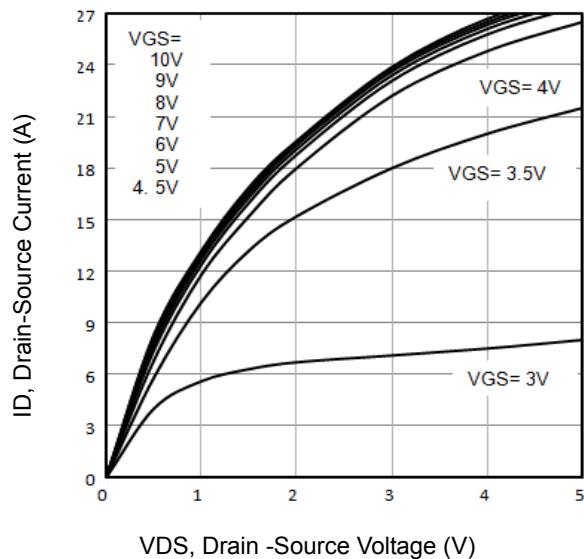


Fig1. Typical Output Characteristics

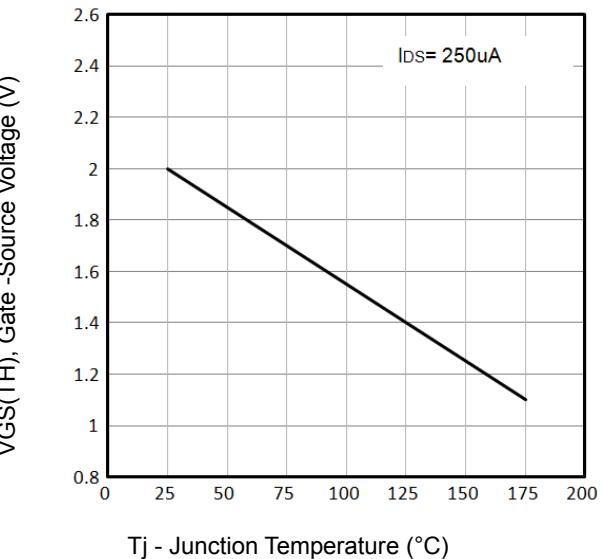


Fig2. $V_{GS(TH)}$ Gate -Source Voltage Vs. T_j

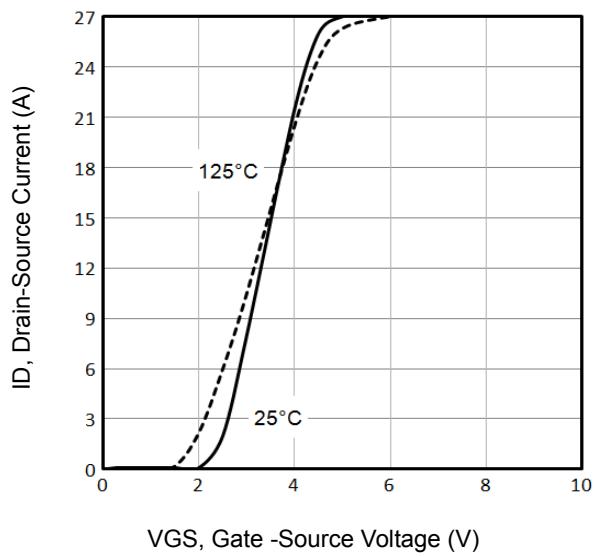


Fig3. Typical Transfer Characteristics

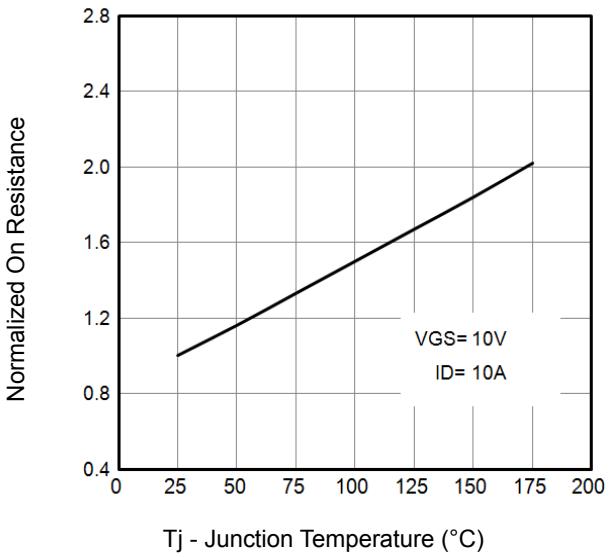


Fig4. Normalized On-Resistance Vs. T_j

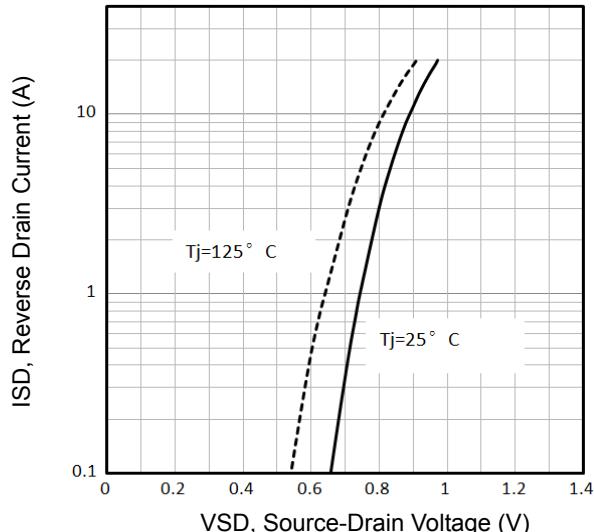


Fig5. Typical Source-Drain Diode Forward Voltage

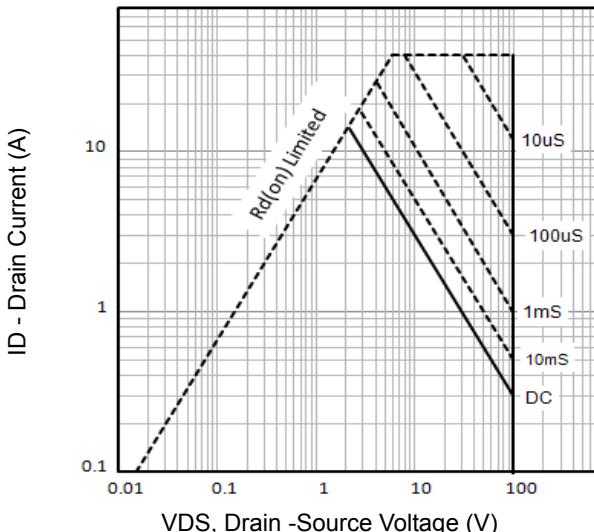


Fig6. Maximum Safe Operating Area

Typical Characteristics

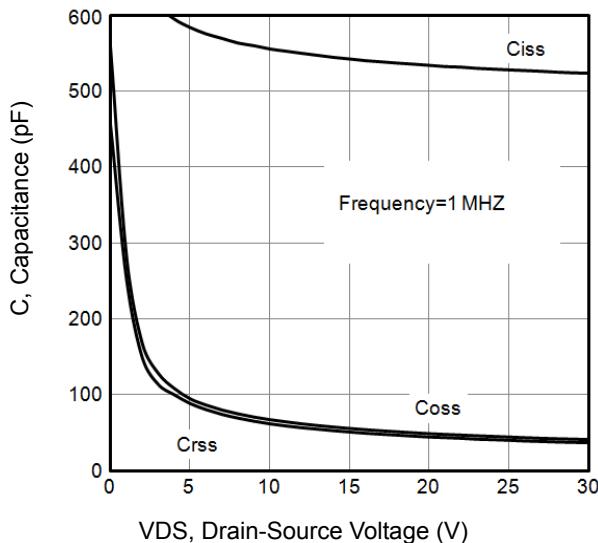


Fig7. Typical Capacitance Vs. Drain-Source Voltage

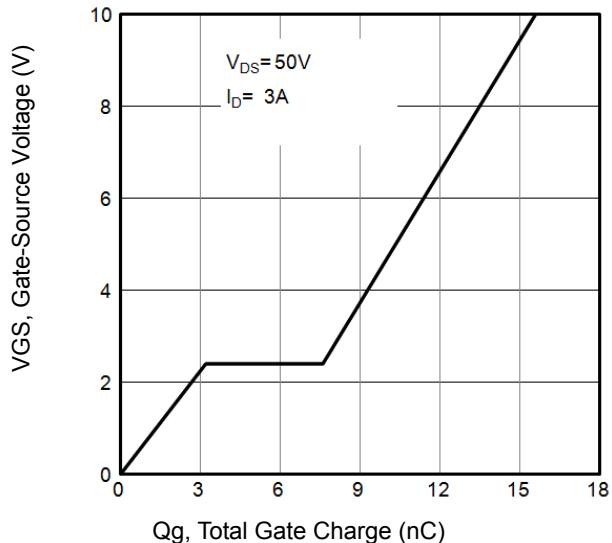


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

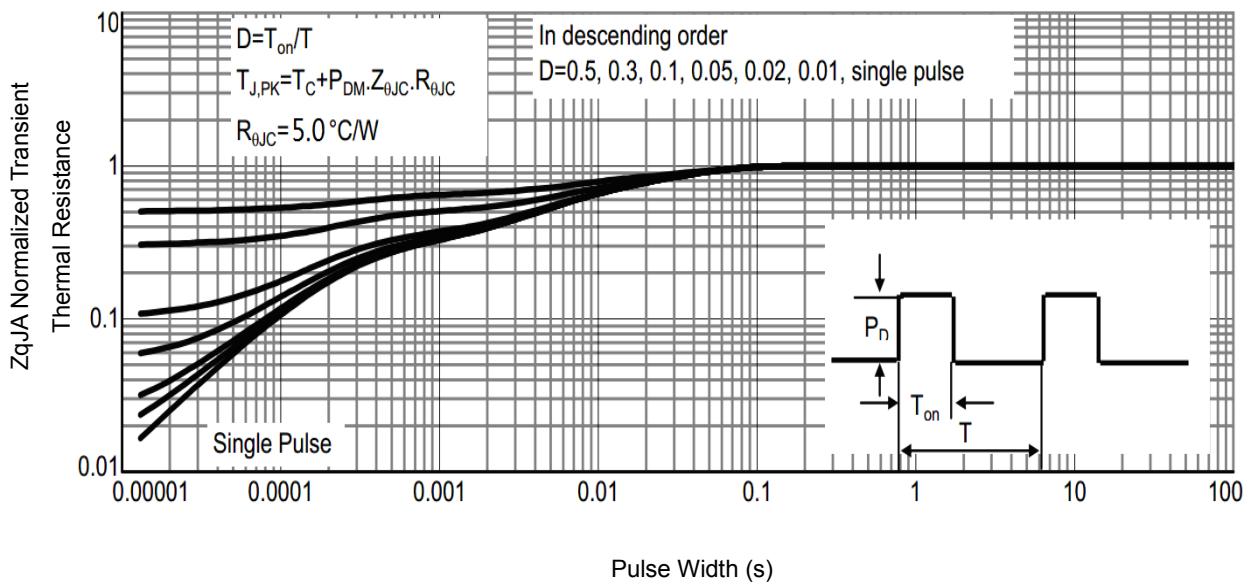


Fig9. Normalized Maximum Transient Thermal Impedance

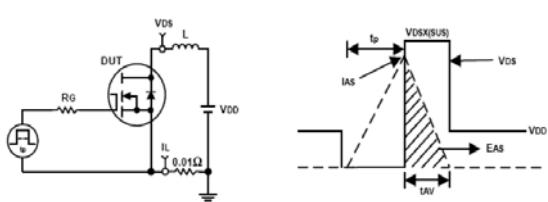


Fig10. Unclamped Inductive Test Circuit and waveforms

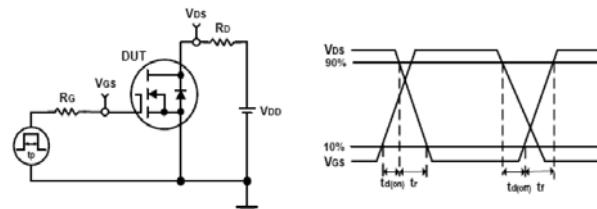
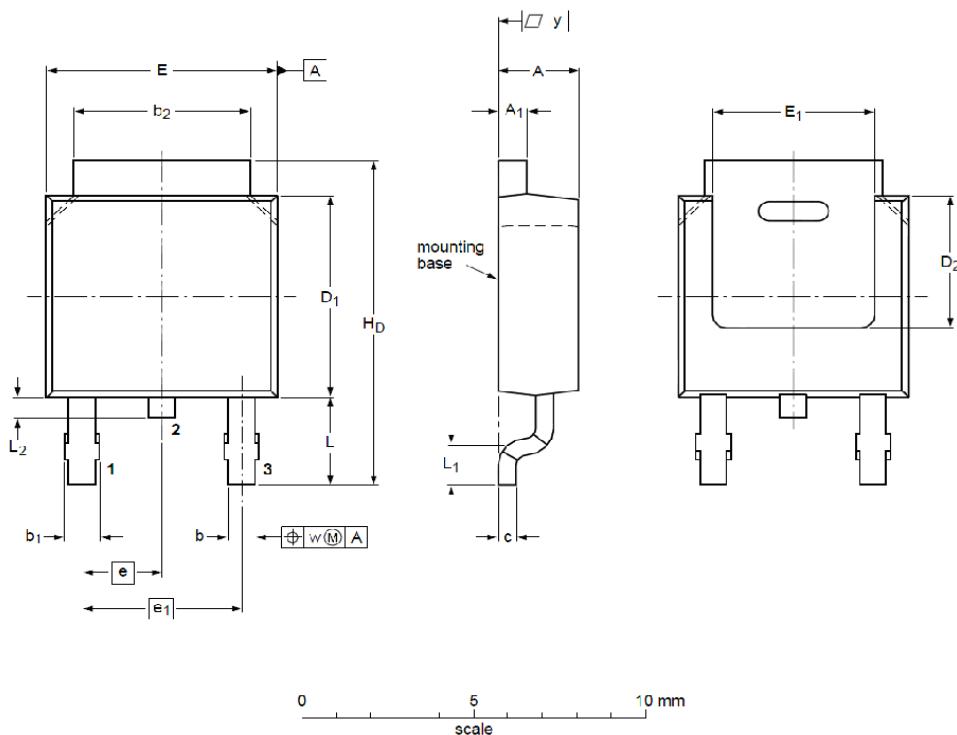


Fig11. Switching Time Test Circuit and waveforms



TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b ₁	0.90	0.98	1.10
b ₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D ₁	5.98	6.05	6.22	D ₂	--	4.00	--
E	6.47	6.60	6.73	E ₁	5.10	5.28	5.45
e	--	2.28	--	e ₁	--	4.57	--
H _D	9.60	10.08	10.40	L	2.75	2.95	3.05
L ₁	--	0.50	--	L ₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

Customer Service

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